



Product Change Notification

113682 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 113682 - 00
Change Title: Intel® SSD DC P3600 Series (1.2TB, 1.6TB, 2.0TB, 400GB, 800GB 2.5in PCIe 3.0, 20nm, MLC),
Intel® SSD DC P3700 Series (1.6TB, 2.0TB, 400GB, 800GB 2.5in PCIe 3.0, 20nm, MLC),
PCN 113682-00
Product Material
Enclosure Second Source
Date of Publication: March 10, 2015

Key Characteristics of the Change:

Product Material

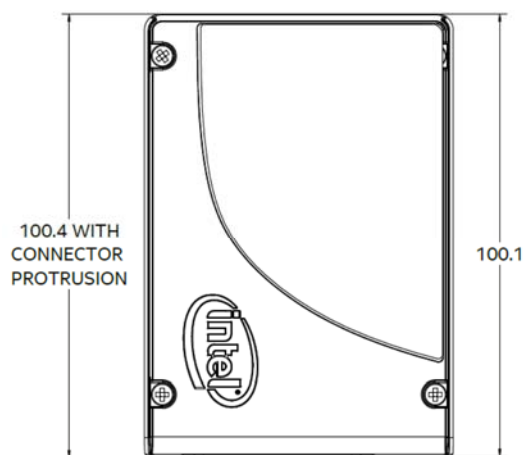
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Mar 20, 2015
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Description of Change to the Customer:

Intel has qualified a second source supplier for the Intel® SSD DC P3700 and P3600 2.5in x 15mm SFF-8639 form factor enclosure. The second source enclosure meets and passes Intel mechanical and dimension requirements, as well as mechanical required tests. These include temperature cycling, temperature humidity bias, shock and vibe. Please contact your Intel representative for full test results.

Primary source is pictured on the top while the secondary source is shown on the bottom.



Customer Impact of Change and Recommended Action:

Since the new enclosure meets the same required quality and reliability criteria as the primary, Intel is not recommending that a customer take any action. The new enclosure meets the current requirements of the SSD Form Factor specification for SFF-8639 enclosure, as well as Intel criteria for form, fit, function, and reliability.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	TA	SA
SSDPE2MD400G401	933079	H26409-204	H26410-204
SSDPE2MD800G401	933080	H26411-204	H26412-204
SSDPE2MD016T401	933081	H26413-204	H26414-204
SSDPE2MD020T401	933082	H26415-204	H26416-204
SSDPE2ME400G401	934670	H34546-204	H34547-204
SSDPE2ME800G401	934671	H34548-204	H34549-204
SSDPE2ME012T401	934672	H34550-204	H34551-204
SSDPE2ME016T401	934673	H34552-204	H34554-204
SSDPE2ME020T401	934674	H34555-204	H34556-204
SSDPE2MD400G410	937360	H47510-203	H26410-204
SSDPE2MD800G410	937361	H48068-203	H26412-204
SSDPE2MD016T410	937362	H47511-203	H26414-204
SSDPE2MD020T410	937363	H47512-203	H26416-204
SSDPE2ME400G410	937368	H47531-203	H34547-204
SSDPE2ME800G410	937370	H47534-203	H34549-204
SSDPE2ME012T410	937371	H47535-203	H34551-204
SSDPE2ME016T410	937372	H47536-203	H34554-204
SSDPE2ME020T410	937373	H47537-203	H34556-204

PCN Revision History:

Date of Revision:

March 10, 2015

Revision Number:

00

Reason:

Originally Published PCN